

HSB123

Silicon Epitaxial Planar Diode for High Speed Switching

REJ03G0546-0200

(Previous: ADE-208-487A)

Rev.2.00

Mar 04, 2005

Features

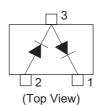
- Low capacitance, proof against high voltage.
- Fast recovery time.
- CMPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

(Previous Code)
PTSP0003ZB-A (CMPAK)

Pin Arrangement





- 1. Cathode
- 2. Anode
- 3. Cathode Anode

Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol Value		Unit
Peak reverse voltage	V_{RM}	85	V
Reverse voltage	V_R	80	V
Peak forward current	I _{FM} * ¹	300	mA
Non-Repetitive peak forward surge current	I _{FSM} * ²	4	А
Average rectified current	lo *1	100	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	−55 to +125	°C

Notes: 1. Two device total.

2. Value at duration of 1 μ s, two device total.

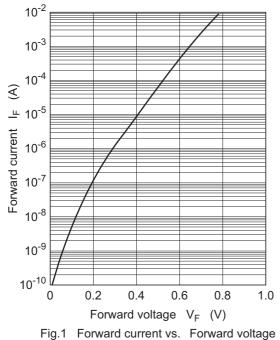
Electrical Characteristics *

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _{F1}	_	_	1.0	V	I _F = 10 mA
	V _{F2}	_	_	1.0		I _F = 50 mA
	V _{F3}	_	_	1.2		I _F = 100 mA
Reverse current	I _R	_	_	0.1	μΑ	V _R = 80 V
Capacitance	С	_	_	2.0	pF	V _R = 0 V, f = 1 MHz
Reverse recovery time	t _{rr}	_	_	3.0	ns	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}, R_L = 50 \Omega$

Note: Per one device.

Main Characteristic



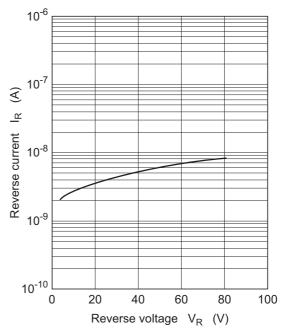
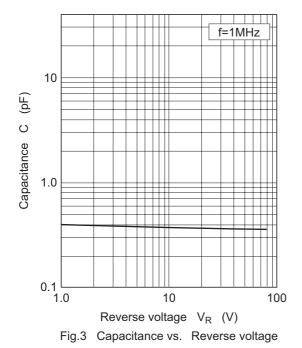
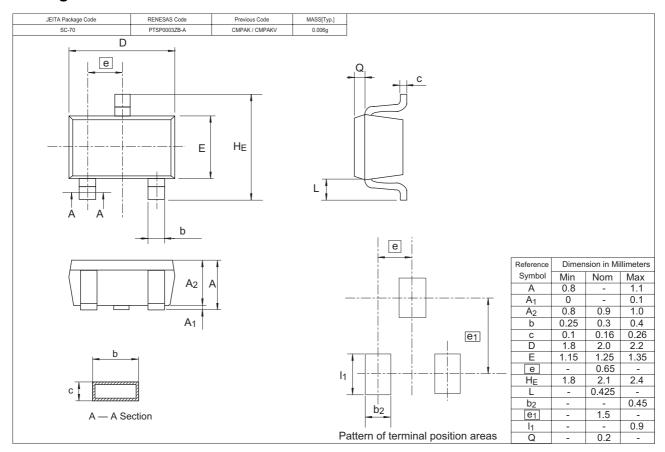


Fig.2 Reverse current vs. Reverse voltage



Package Dimensions



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